Electronic Patent Application Fee Transmittal							
Application Number:	10	10598514					
Filing Date:							
Title of Invention:		MULTIPLE STACKED DIE WINDOW CSP PACKAGE AND METHOD OF MANUFACTURE					
First Named Inventor/Applicant Name:	CH	Chuen Khiang WANG					
Filer:	Da	Daniel Brian Moon/Ramon Linsangan					
Attorney Docket Number:	P2	P26634					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Fi	ling	Fees					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Late filing fee for oath or declaration		1051	1	130	130		
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			130